

Final Product/Process Change Notification Document #: FPCN22382X Issue Date: 20 February 2019

Title of Change:	Addition of Backside Laminate (BSL) and Qualification of Alternative Manufacturing Sites for FAN48610UC50X				
Proposed first ship date:	27 May 2019				
Contact information:	Contact your local ON Semiconductor Sales Office or <steve.frost@onsemi.com></steve.frost@onsemi.com>				
Samples:	Contact your local ON Semiconductor Sales Office or < PCN.samples@onsemi.com > Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.				
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <pete.moberg@onsemi.com></pete.moberg@onsemi.com>				
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact < PCN.Support@onsemi.com				
Change Part Identification:	Affected products will be identified by date code				
Change Category:	☐ Wafer Fab Change	Test Change Other			
Change Sub-Category(s): ✓ Manufacturing Site Addition ✓ Material Change ✓ Manufacturing Site Transfer ✓ Manufacturing Process Change ✓ Monufacturing Process Change		Shipping/Packaging/Marking			
Sites Affected:	ON Semiconductor Sites: ON Cebu, Philippines	External Foundry/Subcon Sites: Amkor Taiwan, ASE-Kaoshiung			
Description and Purpose:					
ON Semiconductor announces t	wo changes affecting FAN48610UC50X:				
 Qualification of a 2nd source manufacturing flow. As indicated in the table below, the device is currently qualified for bump, test, and die sales (saw/T&R/packing) operations in Amkor-Taiwan. Upon expiration or customer approval of the Final PCN, this part will also be qualified for bump at ASE-Kaoshiung and Die Sales operations at OSPI-Cebu (Philippines). No change to the wafer fab or fab process. Upon expiration or customer approval of the Final PCN, the FAN48610UC50X will be produced using Backside Laminate (BSL). Note that there will be no changes to the overall package dimensions. 					
	Before Change Description	After Change Description			
Manufacturing Flow	Wafer Fab (TSMC) →Bump (Amkor TWN) → Probe (Amkor TWN) → Saw/T&R/Pack (Amkor TWN)	Wafer Fab (TSMC) →Bump (Amkor TWN *OR* ASE-K) →Probe (Amkor TWN *OR* OSPI-Cebu Phil) →Saw/T&R/Pack (Amkor TWN *OR* OSPI-Cebu Phil)			
Other Changes	No Backside Laminate (BSL)	With Backside Laminate (BSL)			
There is no product marking change as a result of this change					

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Reliability Data Summary:

QV DEVICE NAME: FAN48680UC08X

iRel F20150542A

PACKAGE Amkor WLCSP-9

Test	Specification	Condition	Interval	Results
TC	JESD22-A104	Ta= -40 °C to +125 °C	850 cyc	0/231
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, @Vccmax	96 hrs	0/231
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C, 3X Reflow, pre TC, HAST, UHAST		

QV DEVICE NAME: FAN48680UC08X

iRel F20150557

PACKAGE ASE WLCSP-9

Test	Specification	Condition	Interval	Results
TC	JESD22-A104	Ta= -40 °C to +125 °C	850 cyc	0/231
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, @Vccmax	96 hrs	0/231
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C, 3X Reflow, pre TC, HAST, UHAST		

Electrical Characteristic Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
FAN48610UC50X	FAN48680UC08X

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